

BRCS200P03ZC

Rev.B Sep.-2024

描述 / Descriptions

PDFN5×6 封装 P 沟道场效应管。

P-Channel MOSFET in a PDFN5×6 Plastic Package.

特征 / Features

$V_{DS}(V)=-30V$ $I_D=-30A$

$R_{DS(ON)}@-10V<20m\Omega$ (TYP. 17.5m Ω)

$R_{DS(ON)}@-4.5V<30m\Omega$ (TYP. 25.5m Ω)

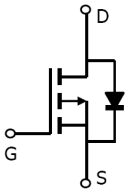
无卤产品。HF Product.

用途 / Applications

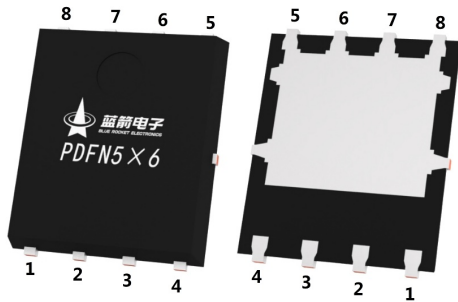
笔记本电脑交流输入负载开关，电池保护充电/放电。

Notebook AC-in Load Switch, Battery Protection Charge/Discharge.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1、2、3: S PIN4: G PIN5、6、7、8: D

印章代码 / Marking

见印章说明。

See Marking Instructions.

极限参数 / Absolute Maximum Ratings($T_a=25^{\circ}\text{C}$)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DS}	-30	V
Drain Current - Continuous	$I_D(T_c=25^{\circ}\text{C})$	-30	A
Drain Current – Pulsed	I_{DM}	-92	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	$P_D(T_c=25^{\circ}\text{C})$	28	W
Single Pulse Avalanche Energy(L=0.5mH)	E_{AS}	152	mJ
Avalanche Current(L=0.5mH)	I_{AS}	19.5	A
Junction and Storage Temperature Range	T_j, T_{stg}	-55 to 150	$^{\circ}\text{C}$
Thermal resistance, junction - ambient	$t \leq 10\text{s}$	$R_{\theta JA}$	$^{\circ}\text{C/W}$
	Steady-State		
Thermal resistance, junction - case	Steady-State	$R_{\theta JC}$	4.5

电性能参数 / Electrical Characteristics($T_a=25^{\circ}\text{C}$)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=-250\mu\text{A}$ $V_{GS}=0\text{V}$	-30	-33		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30\text{V}$ $V_{GS}=0\text{V}$			-1.0	μA
Gate-Body leakage current	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu\text{A}$	-1.3	-1.4	-3.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10\text{V}$, $I_D=-10\text{A}$		17.5	20	m Ω
		$V_{GS}=-4.5\text{V}$, $I_D=-10\text{A}$		25.5	30	
Diode Forward Voltage	V_{SD}	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$			-1.2	V
Input Capacitance	C_{iss}	$V_{DS}=-25\text{V}$ $V_{GS}=0\text{V}$ $f=1.0\text{MHz}$		1430		pF
Output Capacitance	C_{oss}			580		
Reverse Transfer Capacitance	C_{rss}			350		
Gate resistance	R_g	$V_{GS}=0\text{V}$ $V_{DS}=0\text{V}$ $f=1\text{MHz}$		13		Ω
Total Gate Charge	$Q_{g(10V)}$	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $I_D=-9.7\text{A}$		20		nC
Total Gate Charge	$Q_{g(4.5V)}$			9.5		
Gate Source Charge	Q_{gs}			3.5		
Gate Drain Charge	Q_{gd}			4.5		

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=-10V$ $V_{DS}=-15V$ $R_L=1.5\Omega$ $R_{GEN}=3\Omega$		10		ns
Turn-On Rise Time	t_r			5.5		
Turn-Off Delay Time	$t_{d(off)}$			26.1		
Turn-Off Fall Time	t_f			9.1		

电参数曲线图 / Electrical Characteristic Curve

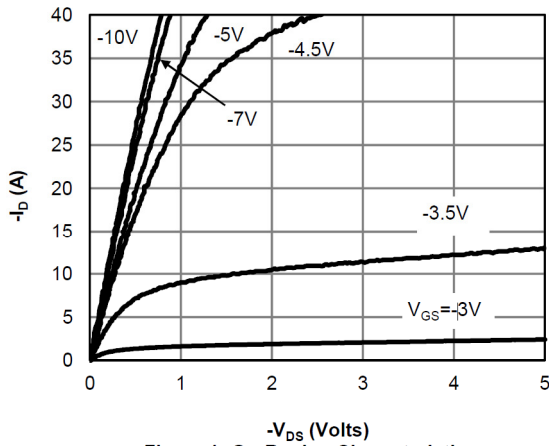


Figure 1: On-Region Characteristics

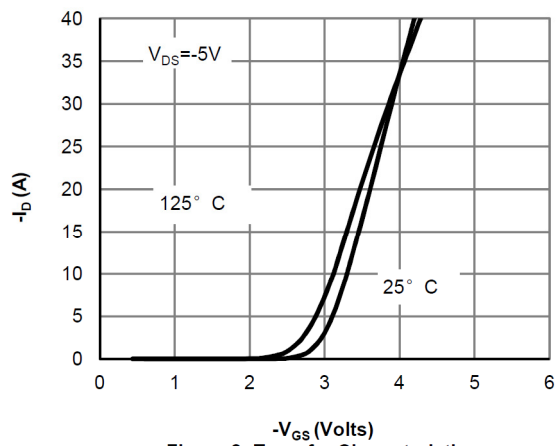


Figure 2: Transfer Characteristics

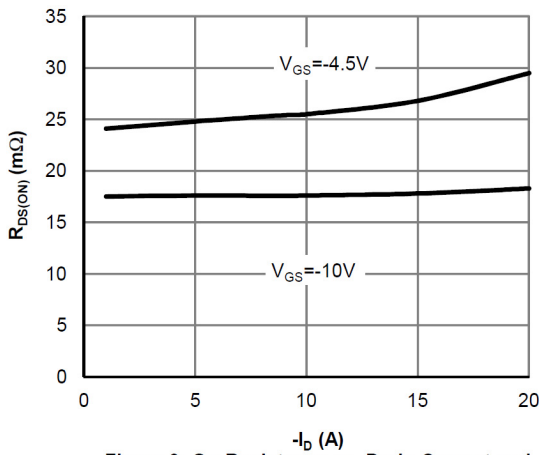


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

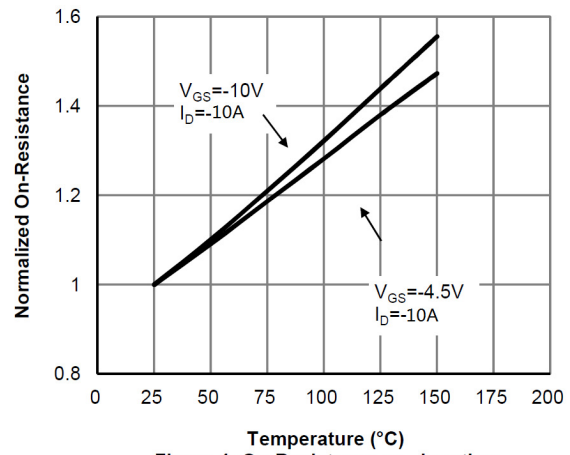


Figure 4: On-Resistance vs. Junction Temperature

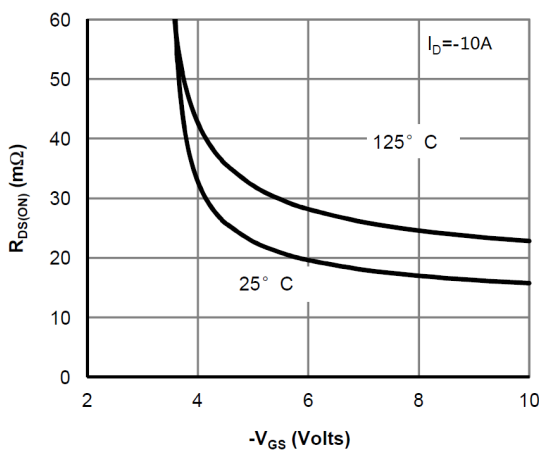


Figure 5: On-Resistance vs. Gate-Source Voltage

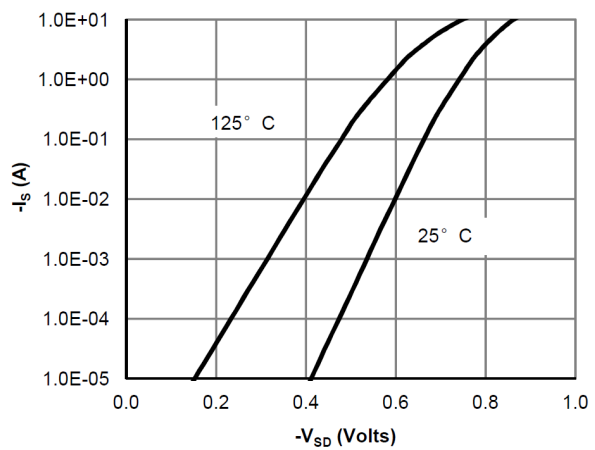


Figure 6: Body-Diode Characteristics

电参数曲线图 / Electrical Characteristic Curve

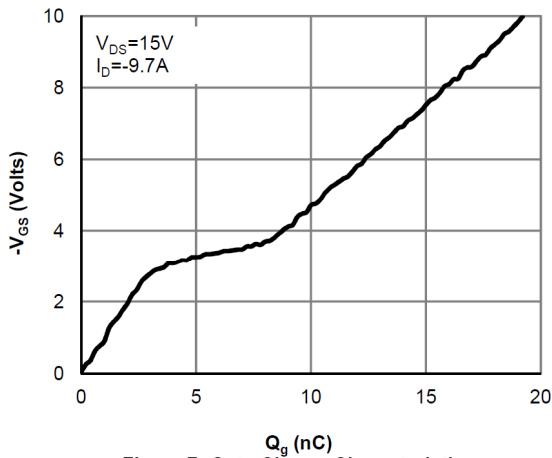


Figure 7: Gate-Charge Characteristics

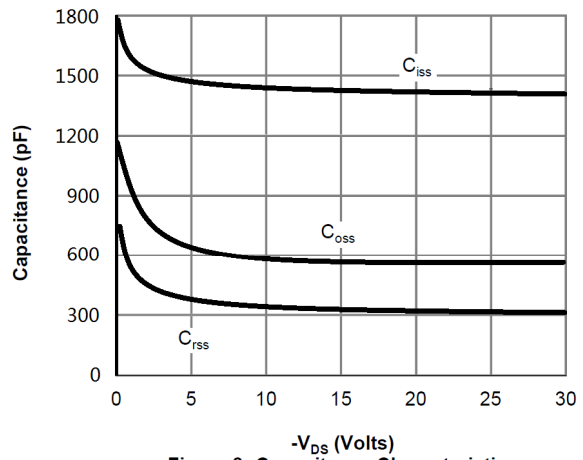


Figure 8: Capacitance Characteristics

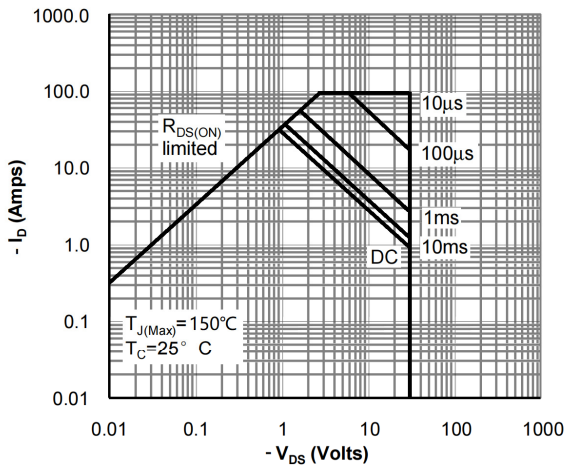


Figure 9: Maximum Forward Biased Safe Operating Area

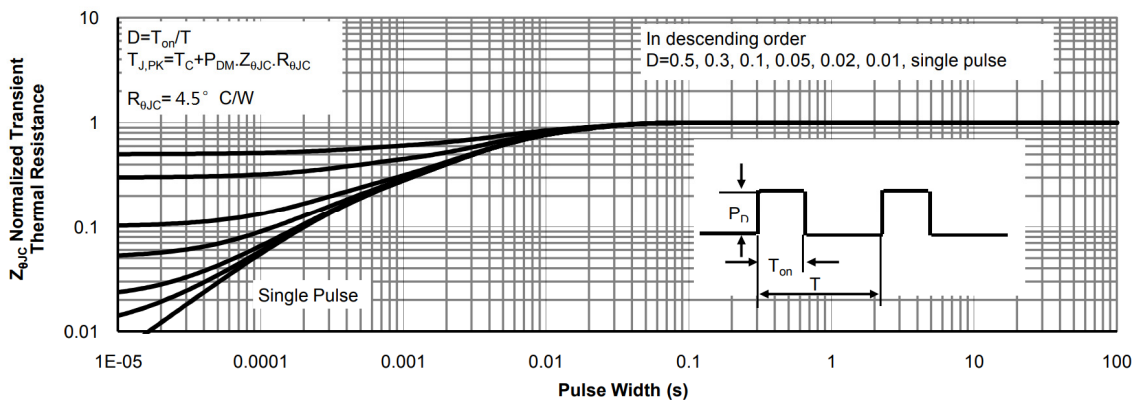
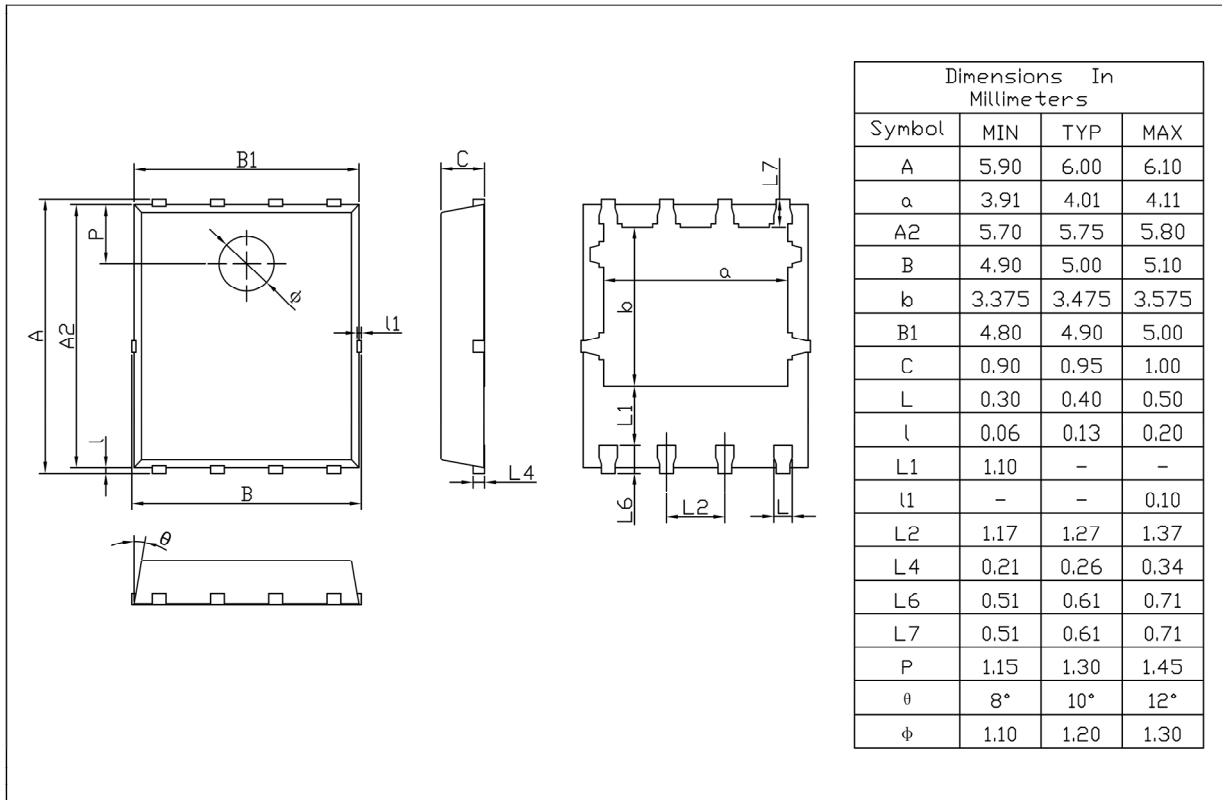


Figure 10: Normalized Maximum Transient Thermal Impedance

外形尺寸图 / Package Dimensions

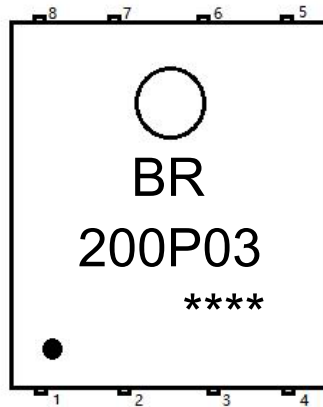
PDFN5 X6

Unit:mm



Rev.01 202209

印章说明 / Marking Instructions



说明：

BR： 为公司代码

200P03： 为型号代码

****： 为生产批号代码，随生产批号变化

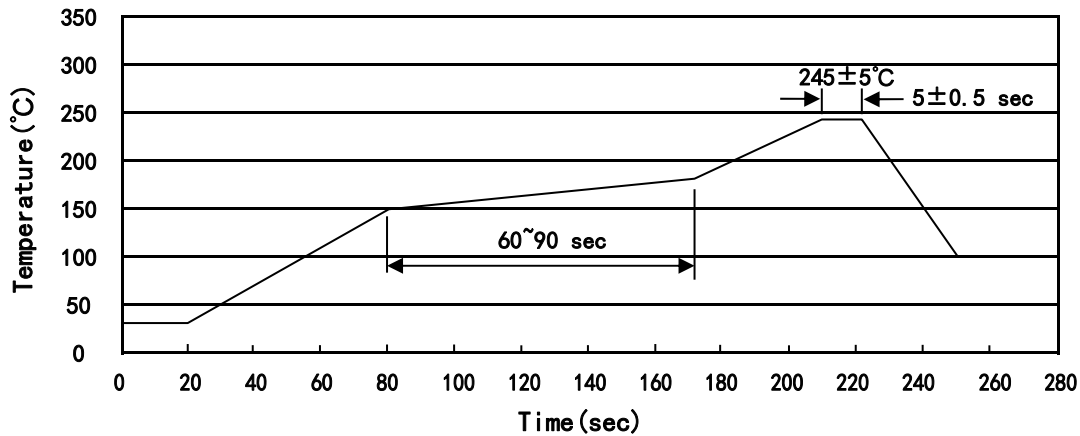
Note：

BR： Company Code

200P03： Product Type Code

****： Lot No. Code, code change with Lot No

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
PDFN5×6	5,000	2	10,000	6	60,000	13"×12	360×360×50	380×335×366

使用说明 / Notices